

IEEE EPS & Malaysia Semiconductor Industry Association (MSIA) Briefing on Advanced Packaging

29th April 2024

Briefing on Advanced Packaging

MSIA together with IEEE EPS is organising a Briefing to members on Advanced Packaging.

Title: **Advanced Packaging Market and Technology Trends**

Date: Monday, 29 April 2024

Time: 3.00pm to 4.30pm

Virtual Call thru Zoom Platform

Presenter:



Dr Tan Yik-Yee
Senior Technology & Market Analyst,
Semiconductor Packaging from Yole Group

Please register here <https://shorturl.at/vKT05>



- The Malaysia Semiconductor Industry Association collaborated with IEEE EPS Malaysia to organize a briefing on Advanced Packaging by **Dr YY Tan** from Yole Intelligence, who is also the past chair of IEEE EPS Malaysia. **Total 121 participants attended the online meeting.**
- Dr YY Tan gave a very clear and informative sharing about **Advanced Packaging Market and Technology Trends** which is a very timely sharing to help Semiconductor companies in Malaysia move forward with Advanced Packaging growth.

